



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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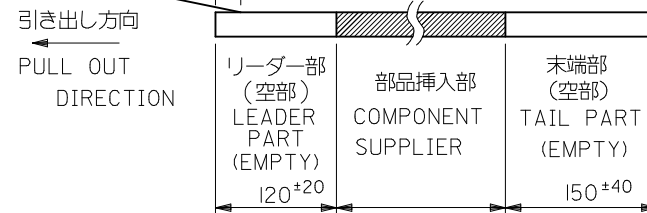
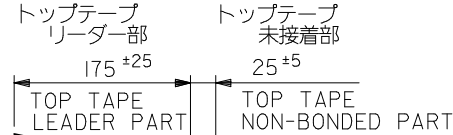


注記 NOTES

1. 製品番号 52746-***39 の梱包状態はアクチュエータがロックした状態とする。
 詳細寸法については図面 SD-52746-025 を参照下さい。
 IN THE PACKAGE,ACTUATOR OF PART NO.52746-***39 SHOULD BE LOCKED
 RE DETAILED DIMENSIONS,SEE SD-52746-025

2. 梱包数量：1000個/リール
 NUMBER OF CONNECTORS:1000PCS/REEL

3. リードテープ長さ LEAD TAPE LENGTH

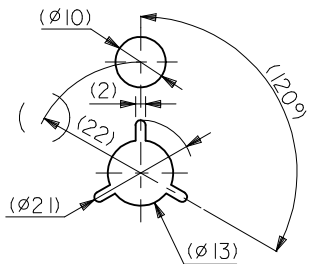
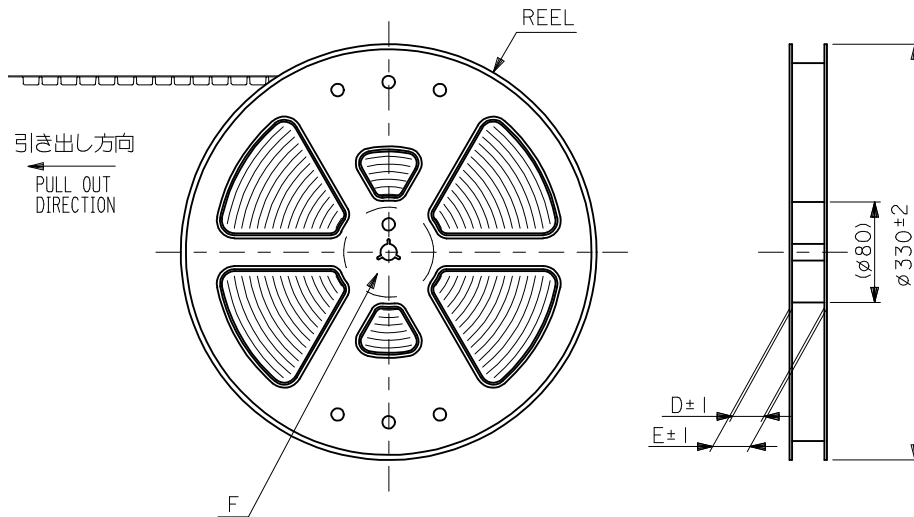
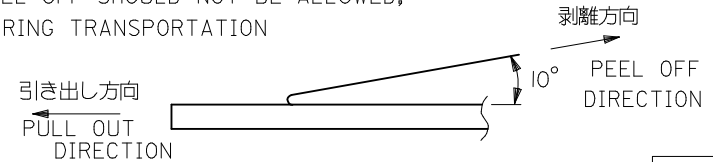


4. トップテープの剥離強度：(剥離方向は下図参照)

0. 1N~1.3N{10gf~130gf} 尚、本規格値は、出荷時に適用。
 (但し、輸送時に剥離が発生しない事。)

PEELING OFF FORCE OF TOP TAPE

0. 1N~1.3N{10gf~130gf}(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
 THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT
 PEEL OFF SHOULD NOT BE ALLOWED,
 DURING TRANSPORTATION



DETAIL F

5. 材料 キャリアテープ：ポリプロピレン (PP)
 トップテープ：PET, PE, PEF
 リール：ポリスチレン (PS) <リサイクル材を含む>

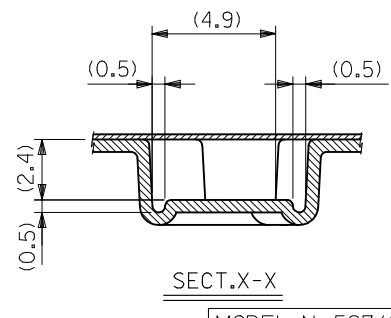
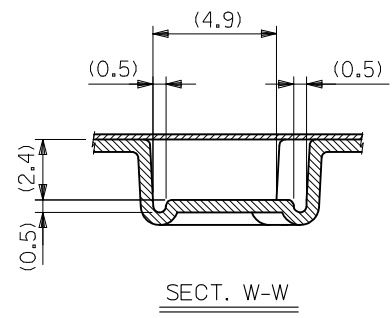
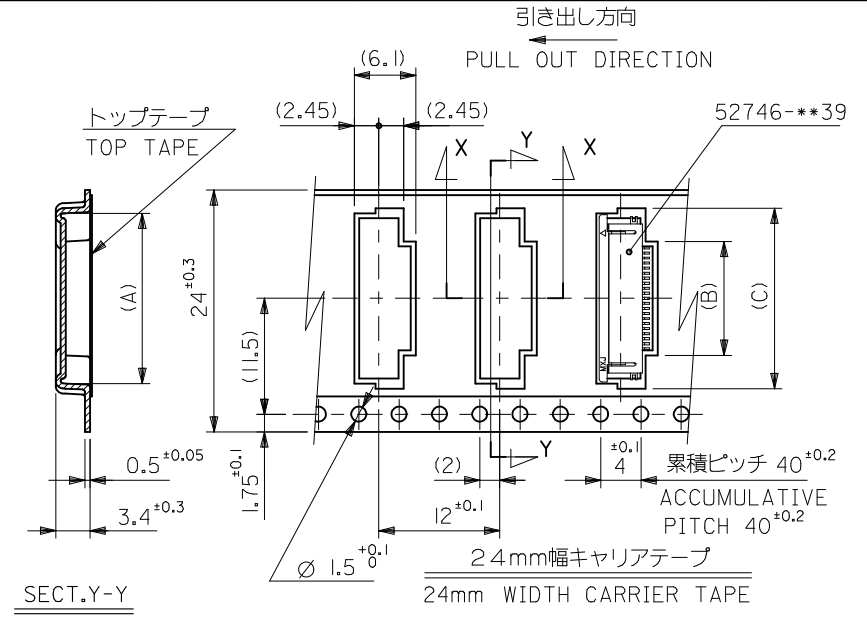
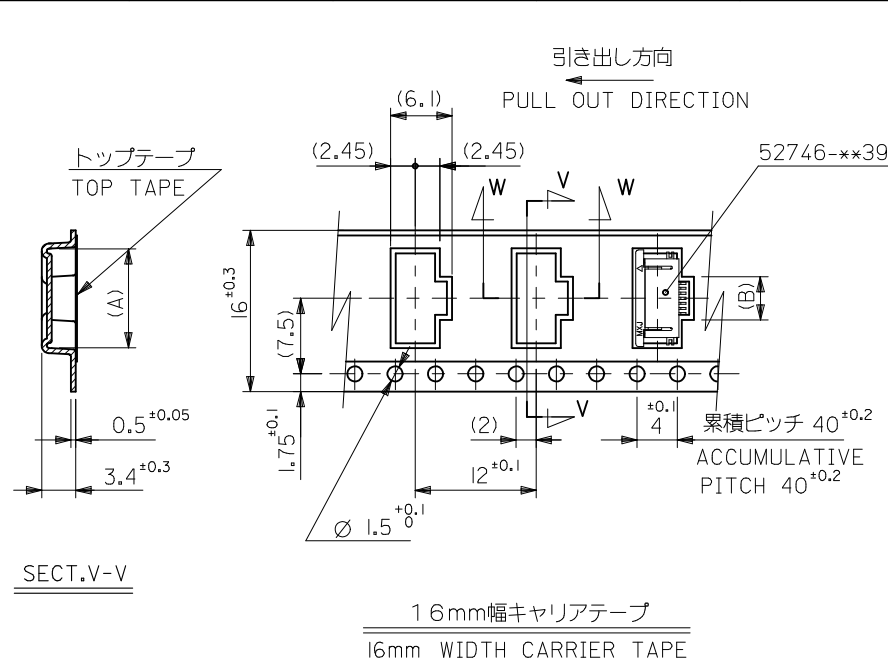
MATERIAL CARRIER TAPE:POLYPROPYLENE
 TOP TAPE:PET,PE,PEF
 REEL:POLYSTYRENE(PS)
 <RECYCLE MATERIAL CONTAINED>

6. 本製品は 52746-***81 の鉛フリー品です
 THIS PRODUCT IS LEAD FREE OF 52746-***81

7. 本製品は乾燥剤入り、ハイバリア梱包仕様である。
 THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

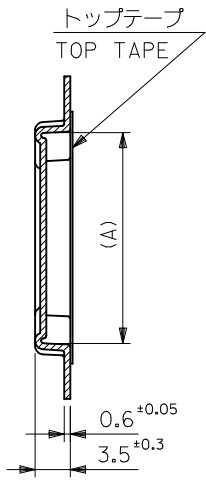
MODEL No.52746-***71

REVISED EC NO: J2015-0443 DRWN:AYOSHI I 01 2014/09/30 CHKD:YKOBAYASHI 02 2014/09/30 APPR:YNOGAWA 2014/10/14	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY HSHIMABUKURO	DATE '04/01/30	TITLE 0.5 FPC CONN ZIF SMT RA B/CONT EMBSTP PKG -LEAD FREE-				
		10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE '04/01/30					
		30 OVER	±0.3	APPROVED BY MSASAO	DATE '04/01/30					
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE SHEET 2,3		DOCUMENT NO. SD-52746-024		SHEET NO. 1 OF 3		
SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION										

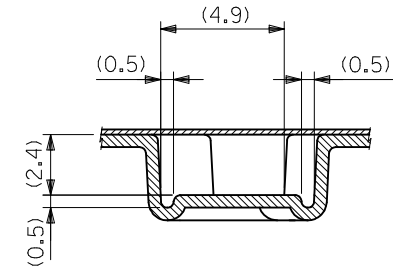
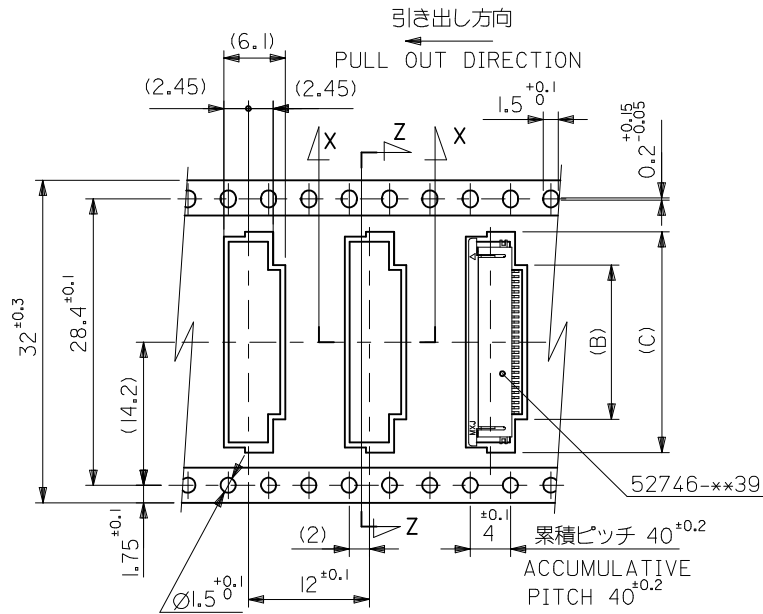


24	29.4	25.4	17.4	10.8	16.4	52746-2071	20
			16.9	10.3	15.9	52746-1971	19
			16.4	9.8	15.4	52746-1871	18
			15.9	9.3	14.9	52746-1771	17
			15.4	8.8	14.4	52746-1671	16
			14.9	8.3	13.9	52746-1571	15
			14.4	7.8	13.4	52746-1471	14
			13.9	7.3	12.9	52746-1371	13
			13.4	6.8	12.4	52746-1271	12
			12.9	6.3	11.9	52746-1171	11
			12.4	5.8	11.4	52746-1071	10
			11.9	5.3	10.9	52746-0971	9
			11.4	4.8	10.4	52746-0871	8
			10.9	4.3	9.9	52746-0771	7
			10.4	3.8	9.4	52746-0671	6
9.4	2.8	8.4	52746-0471	4			
16	21.4	17.4					
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	MATERIAL NO.	極数 CIRCUITS

REVISED EC NO: J2015-0443 DRWN: AYOSHI I 2014/09/30 CHKD: YKOBAYASHI 022014/09/30 APPR: YNOGAWA 2014/10/14	DESCRIPTION REV J	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY HSHIMABUKURO	DATE '04/01/30	TITLE 0.5 FPC CONN ZIF SMT RA B/CONT EMBSTP PKG -LEAD FREE-				
		10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE '04/01/30					
		30 OVER	±0.3	APPROVED BY MSASAO	DATE '04/01/30					
		ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-52746-024		SHEET NO. 2 OF 3
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION										



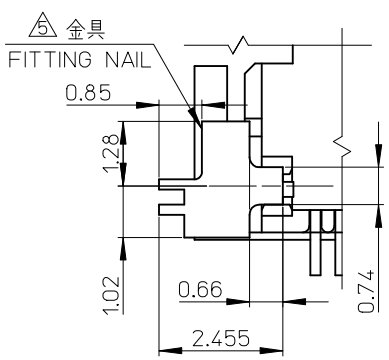
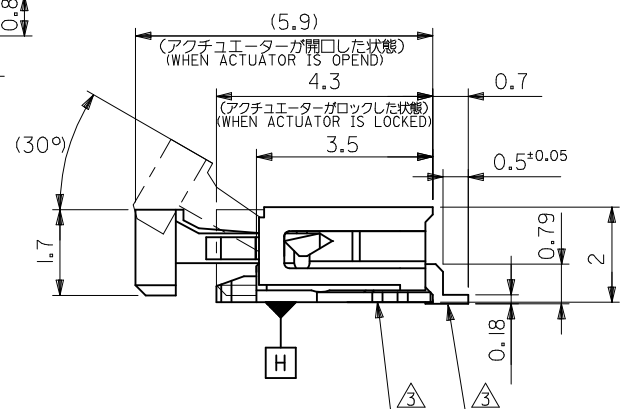
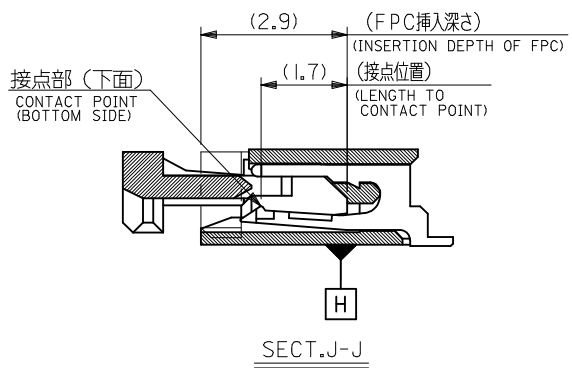
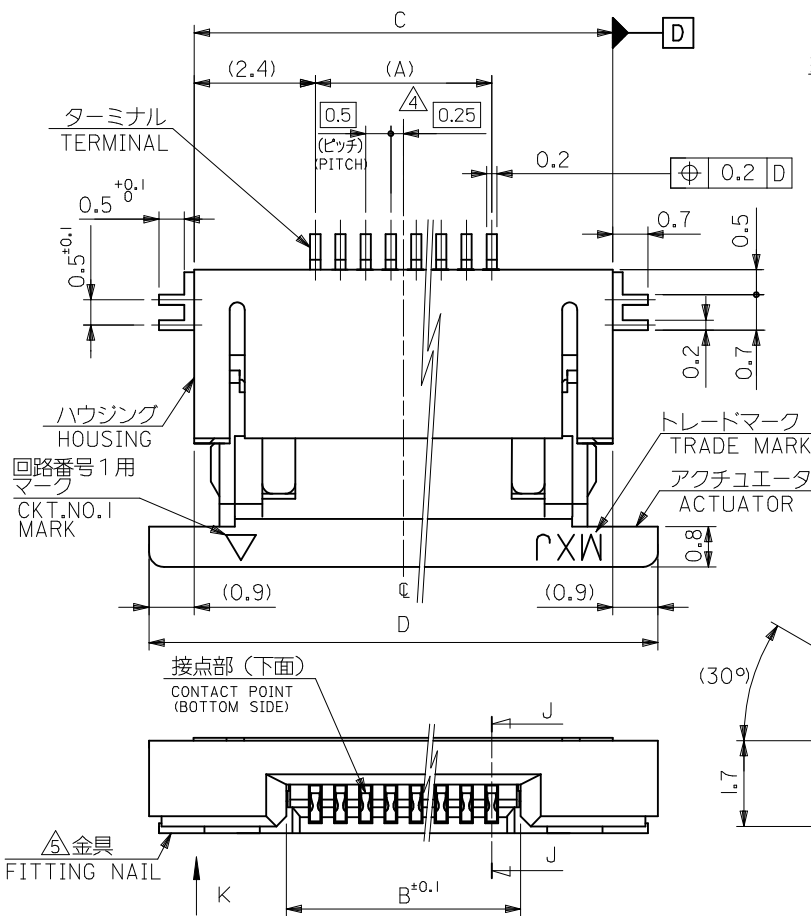
SECT.Z-Z



SECT.X-X

32mm幅キャリアテープ
32mm WIDTH CARRIER TAPE

REVISED EC NO: J2015-0443 DRWN:AYOSHI 2014/09/30 CHKD:YKOBAYASHI 2014/09/30 APPR:YNOGAWA 2014/10/14	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER ±0.2	10 OVER 30 UNDER ±0.25	30 OVER ±0.3	DRAWN BY HSHIMABUKURO	DATE '04/01/30	TITLE 0.5 FPC CONN ZIF SMT RA B/CONT EMBSTP PKG -LEAD FREE-	
	ANGULAR ±3 °			CHECKED BY KTOJO	DATE '04/01/30	APPROVED BY MSASAO	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			MATERIAL NO. SEE TABLE	DATE '04/01/30	DOCUMENT NO. SD-52746-024	SHEET NO. 3 OF 3
J			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

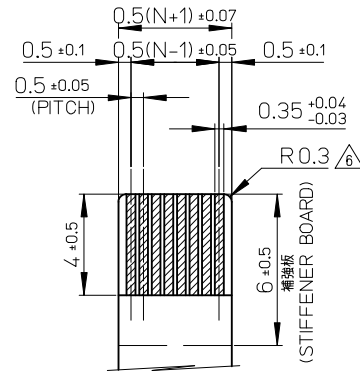


VIEW K
(金具部投影図)
(DETAIL OF FITTING NAIL)

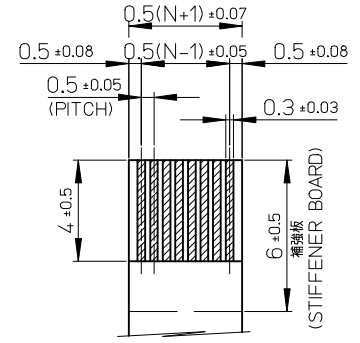
16.1	14.3	10.65	9.5	52746-2071	20
15.6	13.8	10.15	9	52746-1971	19
15.1	13.3	9.65	8.5	52746-1871	18
14.6	12.8	9.15	8	52746-1771	17
14.1	12.3	8.65	7.5	52746-1671	16
13.6	11.8	8.15	7	52746-1571	15
13.1	11.3	7.65	6.5	52746-1471	14
12.6	10.8	7.15	6	52746-1371	13
12.1	10.3	6.65	5.5	52746-1271	12
11.6	9.8	6.15	5	52746-1171	11
11.1	9.3	5.65	4.5	52746-1071	10
10.6	8.8	5.15	4	52746-0971	9
10.1	8.3	4.65	3.5	52746-0871	8
9.6	7.8	4.15	3	52746-0771	7
9.1	7.3	3.65	2.5	52746-0671	6
8.1	6.3	2.65	1.5	52746-0471	4
D	C	B	(A)	EMBOSSED PACKAGE ORDER No. オーダー番号	極数 CKT.

CONNECTOR SERIES NO. : 52746-**39

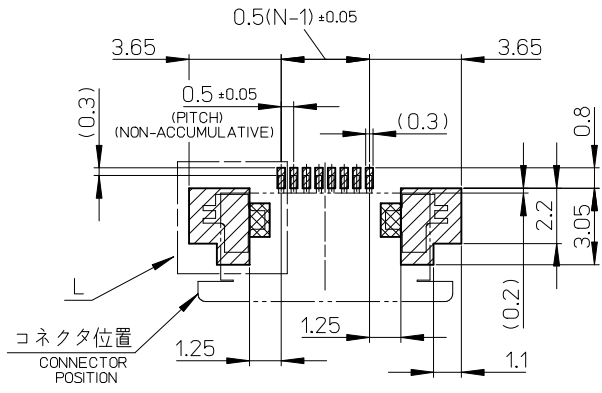
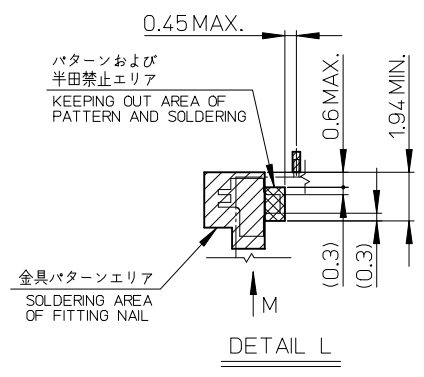
REVISED EC NO: J2015-0443 DRWN:AYOSHI 2014/09/30 CHKD:YKOBAYASHI 2014/09/30 APPR:YNOGAWA 2014/10/14	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY	DATE	TITLE					
	10 OVER 30 UNDER	±0.25	HSHIMABUKURO	'04/01/30	0.5 FPC CONN. ZIF FOR SMT R/A (BOTTOM CONTACT) GOLD PLATING molex					
	30 OVER	±0.3	KTOJO	'04/01/30						
ANGULAR ±3 °		APPROVED BY	DATE	MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MSASAO	'04/01/30	SEE TABLE		SD-52746-025		1 OF 2		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION										



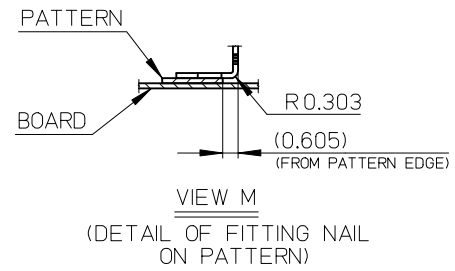
適合金めっきFPC推奨寸法
 APPLICABLE FPC OF GOLD
 PLATING RECOMMENDED DIMENSION
 仕上がり厚さ: 0.3±0.03
 THICKNESS: 0.3±0.03/-0.03



適合金めっきFFC推奨寸法
 APPLICABLE FFC OF GOLD
 PLATING RECOMMENDED DIMENSION
 仕上がり厚さ: 0.3±0.03
 THICKNESS: 0.3±0.03/-0.03



参考基板レイアウト
 (マウント面)
 RECOMMENDED P.C.BOARD
 PATTERN DIMENSION(REF.)
 (MOUNTING SIDE)



VIEW M
 (DETAIL OF FITTING NAIL
 ON PATTERN)

注記NOTES

- 1.使用材料
 MATERIAL
 ハウジング: 46ナイロン、ガラス充填、UL94V-0、白
 HOUSING: PA46, GLASS FILLED, UL94V-0, WHITE
 アクチュエータ: ポリフェニレンサルファイド (PPS)、ガラス充填、UL94V-0、茶色
 ACTUATOR: POLYPHENYLENE SULFIDE, GLASS FILLED, UL94V-0, BROWN
 ターミナル: リン青銅、ニッケル下地金めっき (t=0.2)
 TERMINAL: PHOSPHOR BRONZE, GOLD OVER NICKEL PLATING
 金具: リン青銅、ニッケル下地金めっき (t=0.2)
 FITTING NAIL: PHOSPHOR BRONZE, TIN OVER NICKEL PLATING
2. エンボステープ梱包時は、アクチュエータがロックした状態になります。
 IN THE PACKAGE, ACTUATOR OF PART NO.52746-xx39 SHOULD BE LOCKED.
3. ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面Hに対して上方向に0.1MAXIMUM、下方向0.15MAXIMUMとする。
 MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM DATUM-H.
 UPPER DIRECTION: 0.1MAXIMUM
 LOWER DIRECTION: 0.15 MAXIMUM
4. 偶数極に適用
 APPLY FOR EVEN CIRCUIT.
5. ハ' ターン剥離止め金具
 FITTING NAIL FOR PREVENTION OF PEELING OF P.W.B. PATTERN.
6. R0.3は、FPCの導体部にかからないこと
 R0.3 MUST NOT BE OVERLAPED TO PATTERN OF FPC.
7. ELV 及び RoHS 適合品
 ELV AND RoHS COMPLIANT

FPCについて:
 打ち抜き方向は導体側から補強板を推奨いたします。
 補強フィルム材質はポリイミドを推奨いたします。
 ABOUT FPC:
 RECOMMENDED PUNCHER DIRECTION: FROM CONDUCTOR SIDE TO STIFFNER BOARD SIDE.
 RECOMMENDED MATERIAL:
 STIFFNER FILM: POLYIMIDE
 BONDING AGENT: THERMOSETTING BONDING AGENT

REVISED EC NO: J2015-0443 DRWN: YOSHI 2014/09/30 CHKD: YKOBAYASHI 02/2014/09/30 APPR: YNOGAWA 2014/10/14	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY HSHIMABUKURO	DATE '04/01/30	TITLE 0.5 FPC CONN. ZIF FOR SMT R/A (BOTTOM CONTACT) GOLD PLATING		
	10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE '04/01/30			
	30 OVER	±0.3	APPROVED BY MSASAO	DATE '04/01/30			
ANGULAR ±3 °		MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-52746-025		SHEET NO. 2 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					